

ABSTRACT

EPOXY RESIN COMPOSITION

The present invention relates to an epoxy resin composition comprising a polyphenylene ether having a number average molecular weight of 1,000, to 4,000 and containing components having a molecular weight of 20,000 or more in an amount of substantially 20% or less, and an epoxy resin. The present invention further relates to an epoxylated polyphenylene ether resin obtained by reacting a phenolic hydroxyl group of a polyphenylene ether having a number average molecular weight of 1,000 to 4,000 with an epoxy group of an epoxy compound or an epoxy resin.